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IN THE CLAIMS:

1. (Previously Presented) A multi-zoned processing pad assembly for processing a substrate, comprising:
 - a conductive layer;
 - an upper layer having a non-conductive processing surface coupled to the conductive layer;
 - a conductive surface positioned substantially coplanar with the non-conductive processing surface, wherein a side of the substrate disposed on the upper layer contacts the conductive and non-conductive processing surface; and
 - at least two zones of different current permeability defined across the processing surface of the upper layer, wherein the at least two zones are defined by an attribute of the upper layer.
2. (Original) The assembly of claim 1, further comprising at least one aperture formed through the upper layer and the conductive layer.
3. (Original) The assembly of claim 1, wherein the at least two zones are formed via at least two sets of a plurality of holes in at least the upper layer, wherein the holes in each set of holes have substantially equal spacing but different diameters.
4. (Original) The assembly of claim 1, wherein the at least two zones are formed via at least two sets of a plurality of holes in at least the upper layer, wherein the holes in each set of holes have substantially equal diameters but different spacing.
5. (Original) The assembly of claim 1, wherein the at least two zones are formed via at least two sets of a plurality of holes in at least the upper layer, wherein the holes in each set of holes have different diameters and different spacing.